

L Number	Hits	Search Text	DB	Time stamp
21	2536	((438/633) or (438/692) or (438/693)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/01 21:21
22	1102	((((438/633) or (438/692) or (438/693)).CCLS.) and (cmp or (chemical adj mechanical adj planariz\$5)) and (conduct\$3 or metal) and (slurry or slurries))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/01 21:46
23	6	((((438/633) or (438/692) or (438/693)).CCLS.) and (cmp or (chemical adj mechanical adj planariz\$5)) and (conduct\$3 or metal) and (slurry or slurries)) and (surfactant same silicone)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/01 21:46
24	72	((((438/633) or (438/692) or (438/693)).CCLS.) and (cmp or (chemical adj mechanical adj planariz\$5)) and (conduct\$3 or metal) and (slurry or slurries)) and (surfactant same (silicon or silicone))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 21:46
25	0	(((((438/633) or (438/692) or (438/693)).CCLS.) and (cmp or (chemical adj mechanical adj planariz\$5)) and (conduct\$3 or metal) and (slurry or slurries)) and (surfactant same silicone)) and (hlb or (hydrophile near2 lipophile near5 balance))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 21:46
26	0	(((((438/633) or (438/692) or (438/693)).CCLS.) and (cmp or (chemical adj mechanical adj planariz\$5)) and (conduct\$3 or metal) and (slurry or slurries)) and (surfactant same (silicon or silicone))) and (hlb or (hydrophile near2 lipophile near5 balance))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 21:31
27	6164	(cmp or (chemical adj mechanical adj planariz\$5)) and (conduct\$3 or metal) and (slurry or slurries)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/01 21:46
28	57	((cmp or (chemical adj mechanical adj planariz\$5)) and (conduct\$3 or metal) and (slurry or slurries)) and (surfactant same silicone)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/01 21:46
29	221	((cmp or (chemical adj mechanical adj planariz\$5)) and (conduct\$3 or metal) and (slurry or slurries)) and (surfactant same (silicon or silicone))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 21:46
30	2	((((cmp or (chemical adj mechanical adj planariz\$5)) and (conduct\$3 or metal) and (slurry or slurries)) and (surfactant same silicone)) and (hlb or (hydrophile near2 lipophile near5 balance))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/01 21:47